ALLIANCE MEMORY

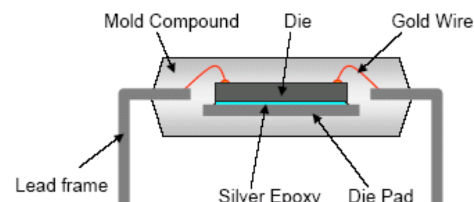
Material Declaration

Comliance Date: **May./21/2024**

RoHS Compliance: **Yes**

MSL: **1**

Pin count /Package	**28L 300mil PDIP**
Model (Part) Number	**AS7C256C-15PCN**
Package Weight (mg)	**2,154.41**



Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total Mass	Material wt% of Sub part
Chip	Wafer Circuit	12.05	0.56	5,593	Silicon (Si)	7440-21-3	12.050	0.559%	100.00%
Bonding Wire	Conductivity	1.2	0.06	557	Gold (Au)	7440-57-5	1.200	0.056%	100.00%
Die Attach	Conductivity	0.70	0.03	325	Silver Power	7440-22-4	0.525	0.024%	75.00%
					Bisphenol F Type Epoxy Resin	9003-36-5	0.028	0.001%	4.00%
					Epoxy resin	Trade secret	0.042	0.002%	6.00%
					Diluent	Trade secret	0.028	0.001%	4.00%
					Ethylene dimethacrylate	97-90-5	0.042	0.002%	6.00%
					1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0	0.030	0.001%	4.25%
					Dicyandiamide	461-58-5	0.002	0.000%	0.25%
					1,1-Di(t-butylperoxy)cyclohexan	3006-86-8	0.004	0.000%	0.50%
Lead Frame	Base Metal	338.96	15.73	157,333	Copper (Cu)	7440-50-8	318.250	14.772%	93.89%
					Iron (Fe)	7439-89-6	7.864	0.365%	2.32%
					Zinc (Zn)	7440-66-6	0.644	0.030%	0.19%
	impurity				Phosphorus (P)	7723-14-0	0.339	0.016%	0.10%
	Plating area				Silver (Ag)	7440-22-4	11.864	0.551%	3.50%
Molding Compound	Chip Protection	1780.50	82.64	826,444	Silica(Amorphous) A	60676-86-0	1476.035	68.512%	82.90%
					Silica(Amorphous) B	7631-86-9	94.367	4.380%	5.30%
					Epoxy Resin A	Trade secret	89.025	4.132%	5.00%
					Epoxy Resin B	29690-82-2	53.415	2.479%	3.00%
					Phenol Resin	Trade secret	62.318	2.893%	3.50%
					Carbon Black	1333-86-4	5.342	0.248%	0.30%
Plating of lead frame	Solder Plating	21.00	0.97	9,747	Tin (Sn)	7440-31-5	20.998	0.975%	99.99%
	impurity				Lead (Pb)	7439-92-1	0.002	0.0001%	0.01%